Claims

1. Method for forming an electronic component package, comprising the steps of:

A) providing at least one housing with at least one enclosed opening for an electronic component, which housing is at least partially made out of a partially cured moulding material;

B) placing the partially cured housing on a carrier comprising at least one electronic component mounted on the carrier such that the housing encloses the electronic component mounted on the carrier;

C) placing the carrier in a mould, such that the carrier and the at least one electronic component lie between a contact surface of a first mould part and a contact surface of a second mould part;

D) moving the mould parts toward each other and holding the mould parts in a closed position under the influence of a closing force, whereby at least one mould cavity in the contact surface of at least one of the mould parts encloses the electronic component and the housing;

E) introducing a liquid moulding material into the at least one mould cavity, such that the liquid moulding material fills the mould cavity leaving the at least one housing opening free of moulding material;

F) allowing the liquid moulding material to at least partially cure and integrate with at least a part of the at least one housing to form an electronic component package; and

G) moving the mould parts apart and taking the electronic component package out of the mould.

2. Method according to claim 1, **characterised in that** the partially cured material of the housing during processing step B) comprises B-stage cured material.

3. Method according to claim 1 or 2, **characterised in that** the moulding material comprises epoxy and/or an epoxy moulding compound (EMC).

4. Method according to any one of the claims 1 – 3, **characterised in that** the moulding process is performed by transfer moulding or compression moulding.

5. Method according to any one of the claims 1 – 4, **characterised in that** the partially cured moulding material of the housing, in particular prior to partial curing, and the liquid moulding material introduced in step E) are a same material.

6. Housing with at least one enclosed opening for holding an electronic component mounted on a carrier, which housing is at least partially made of a partially cured moulding material and which opening borders a flat contact side to be placed onto a carrier.

7. Housing according to claim 6, **characterised in that** the partially cured material comprises B-stage cured material.

8. Housing according to claims 6 or 7, **characterised in that** the moulding material comprises epoxy and/or an epoxy moulding compound (EMC).

9. Housing according to any one of the claims 6 - 8, **characterised in that** the housing comprises a top cover facing away from the contact side of the housing.

10. Housing according to claim 9, **characterised in that** the top cover comprises at least one aperture.

11. Housing according to claim 9 or 10, **characterised in that** the top cover is made of a material chosen from the group of epoxy, an epoxy moulding compound (EMC), glass, silicon and metal.

12. Housing according to any one of the claims 6 – 11, **characterised in that** the housing comprises a plurality of housing openings.

13. Electronic component package comprising:

- a carrier whereon at least one electronic component is mounted that is enclosed by at least one housing according to any one of the claims 6 – 12, which housing is attached to the carrier; and
- surrounding moulding material attached to the carrier, which surrounding moulding material is surrounding the at least one housing,

wherein the surrounding moulding material and the housing are fully cured;
wherein the surrounding moulding material and at least a part of the at least one housing are made out of a same material, and
wherein the surrounding moulding material and at least a part of the material of the at least one housing are integrated.

14. Electronic component package according to claim 13, **characterised in that** the moulding material of the at least part of the housing and the surrounding moulding material are fused.

15. Electronic component package obtainable by the method according to any one of the claims 1 – 5.